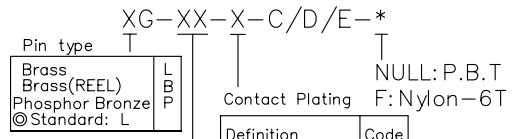
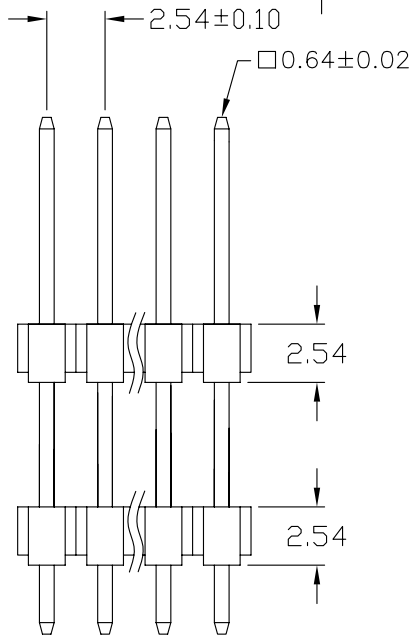
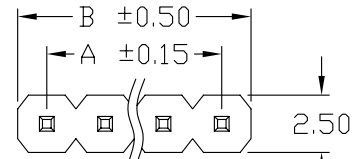


No. of Contacts	DIMENSIONS	
	A	B
1		2.54
2	2.54	5.08
3	5.08	7.62
4	7.62	10.16
5	10.16	12.70
6	12.70	15.24
7	15.24	17.78
8	17.78	20.32
9	20.32	22.86
10	22.86	25.40
11	25.40	27.94
12	27.94	30.48
13	30.48	33.02
14	33.02	35.56
15	35.56	38.10
16	38.10	40.64
17	40.64	43.18
18	43.18	45.72
19	45.72	48.26
20	48.26	50.80
21	50.80	53.34
22	53.34	55.88
23	55.88	58.42
24	58.42	60.96
25	60.96	63.50
26	63.50	66.04
27	66.04	68.58
28	68.58	71.12
29	71.12	73.66
30	73.66	76.20
31	76.20	78.74
32	78.74	81.28
33	81.28	83.82
34	83.82	86.36
35	86.36	88.90
36	88.90	91.44
37	91.44	93.98
38	93.98	96.52
39	96.52	99.06
40	99.06	101.60



Definition	Code
◎ Tin plated:	A
◎ Gold plated:	
flash B	15μ" F
10μ" E	30μ" J
◎ Duplex plating:	
flash K	15μ" P
10μ" N	30μ" U
◎ Standard:	B
◎ Prefix "V" means	lead free plating.

SPECIFICATIONS

Current Rating: 3 Amps
 Insulator resistance: 5000 Megohms min.
 Dielectric withstanding: AC 500 V
 Operating Temperature: -40°~+105°C
 Contact Material: Copper Alloy
 Insulator Material: Thermoplastic, UL 94V-0
 Color: Black

Finish: Tin, Gold or Duplex plated
 ◎ Standard: Gold flash all over
 ◎ Note: Duplex plating: gold plated on contact area, Tin on solder area

Recommended PCB Layout
 (PCB TOLERANCE ±0.05)

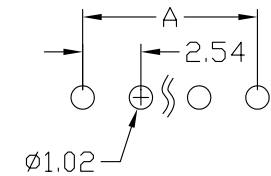


Diagram	Molding description
○	mass production & assemble mold
◎	sample & assemble mold
⊕	mass production & fix mold
⊗	sample & fix mold

Rev.	ECN Number	Description	Drawn	Date
51	EC2-580067	新增 XG-XX-X-120/051/060-*	陳顯鑫	08/11 05'
52	EC3-5A0099	新增 XG-XX-X-030/105/030-*	陳顯鑫	10/26 05'
53	EC3-610073	新增 XG-XX-X-105/260/025-*	詹益東	01/24 06'



GENERAL TOLERANCE		SCALE	ORIGINAL DRAWN
XX. ± 0.50	XXX. ±	3=1	邱若婷
X. ± 0.30	.XXX ±	UNIT	林錫錦
.X ± 0.25	X.° ± 4°	MM	林錫錦
.XX ± 0.20	.X° ± 4°	SIZE A4	APPROVE

DATE	CHECK	APPROVE
24-02-04'	林錫錦	林錫錦
01/24 06'		
01/24 06'		

DWG. NO.	PARTS NO.	TITLE	REV.
X-XX	XG-XX-X-C/D/E-*	2.54mm BOARD STACKER (成品規格圖)	53
F: \DWG\CDWG\G\GS6M.DWG			SHEET 1/2